

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
02008.073001; AD-0069PCTUS

In Re Application Of: **Kouichi WADA et al.**

10/031823
13 Rec'd PCT/PTO 13 JUN 2002

Serial No.
10/031,823

Filing Date
January 18, 2002

Examiner

Group Art Unit

Title: **PROBE CARD AND METHOD OF PRODUCING THE SAME**

Address to:
Assistant Commissioner for Patents
Washington, D.C. 20231

37 CFR 1.97(b)

1. ☒ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application; within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or before the mailing date of a first Office Action on the merits, whichever event occurs last.

37 CFR 1.97(c)

2. ☐ The Information Disclosure Statement submitted herewith is being filed after three months of the filing of a national application, or the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or after the mailing date of a first Office Action on the merits, whichever occurred last but before the mailing date of either:

1. a Final Action under 37 CFR 1.113, or
2. a Notice of Allowance under 37 CFR 1.311,

whichever occurs first.

Also submitted herewith is:

- ☐ a certification as specified in 37 CFR 1.97(e);

OR

- ☐ the fee set forth in 37 CFR 1.17(p) for submission of an Information Disclosure Statement under 37 CFR 1.97(c).

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Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- ☐ A check in the amount of _____ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **50-0591** as described below. A duplicate copy of this sheet is enclosed.
- ☐ Charge the amount of _____
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I certify that this document and authorization to charge deposit account is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. _____) on _____ (Date)

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*This certificate may only be used if paying by deposit account.

Dated: **6/13/02**

#45,079
Signature

Jonathan P. Osha, Reg. No. 33,986
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CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.1)Applicant(s): **Kouichi WADA et al.**

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Invention: **PROBE CARD AND METHOD OF PRODUCING THE SAME**I hereby certify that this **Information Disclosure Statement***(Identify type of correspondence)*

is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to: The Commissioner of Patents and Trademarks, Washington, D.C.

20231-0001 on **13 June 2002***(Date)***EV049242838US***(Typed or Printed Name of Person Mailing Correspondence)*
*(Signature of Person Mailing Correspondence)***Toni A. Hill***("Express Mail" Mailing Label Number)***Note: Each paper must have its own certificate of mailing.**

Related Art(s) for Information Disclosure

Your Ref.

Our Ref. AD-0069PCTUS

RE (Title) PROBE CARD AND A METHOD FOR MANUFACTURING THEREOF

List of Attached Document(s)

1. Document(s) discussed in the specification of the present Patent Application or written in English

(1) US patent No. 5,613,861

(2) Donald L. Smith, et. Al., in their "Flip-Chip Bonding on 6-um Pitch using Thin-Film Microspring Technology"((Proceedings of 48th Electronic Components and Technology Conf.; Seattle, Washington (May, 1998):c1998 IEEE)

(3) Soonil Hong, et. Al., in their "DESIGN AND FABRICATION OF A MONOLITHIC HIGH-DENSITY PROBE CARD FOR HIGH-FREQUENCY ON-WATER TESTING"(IEDM 89, pp.289-292)

(4) Yanwei Zhang, et. Al., in their "A NEW MEMS WAFER PROBE CARD"
(0-7803-3744-1/97 IEEE, pp.395-399)

(5) Shinichiro Asai, et. Al., in their "Probe Card with Probe Pins Grown by the Vapor-Liquid-Solid(VLS) Method" (IEEE TRANSACTIONS ON COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY-PART A, VOL.19, NO.2, JUNE 1996)

2. Other Document(s) (with concise explanation regarding the relevancy)

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.
02008.073001; AD-0069PCTUSSERIAL NO.
10/031,823

Kouichi WADA et al.

FILING

January 18, 2002

GROUP

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	A1	5,613,861	03/25/1997	Smith et al.	439	81	06/07/1995

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

		A2	Donald L. Smith et al., "Flip-Chip Bonding on 6-um Pitch using Thin-Film Microspring Technology," Proceedings of the 48th Electronic Components and Technology Conference; Seattle, Washington; May 1998; copyright 1998 IEEE; 3 pages
		A3	Soonil Hong et al., "DESIGN AND FABRICATION OF A MONOLITHIC HIGH-DENSITY PROBE CARD FOR HIGH-FREQUENCY ON-WATER TESTING," IEDM 89, pp. 289-292 (4 pages)

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

(Use several sheets if necessary)

SERIAL NO. 10/031,823

FILING

January 18, 2002

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		B1	Yanwei Zhang et al.; "A NEW MEMS WAFER PROBE CARD," 0-7803-3744-1/97 IEEE, pp. 395-399 (5 pages)
		B2	Shinichiro Asai et al.; "Probe Card with Probe Pins Grown by the Vapor-Liquid-Solid(VLS) Method;" IEEE Transactions on Components, PACKAGING AND MANUFACTURING TECHBNOLGY-Part A, Vol. 19, No. 2, June 1996; pp. 258-267 (10 pages)

DATE CONSIDERED

PAGE 2 OF 2